

自動晶圓撕膜機

c sun

Auto De-taping Machine

MP-A12W



機台特點 Characteristics

- 選用軟性材料接觸，保護產品，避免損傷
Use soft materials to protect the product and avoid damage
- 提供良好的靜電消除能力
Provides good static elimination ability
- 提供UV及熱解膠選擇方案，為各種製程提供良好的解決方案
Provide UV and pyrolysis adhesive options to provide good solutions for various processes



Leading in Thermal and UV Light Processing Equipment

MP-A12W

適用範圍 Wafer Dimension	WAFER直徑：12" WAFER厚度：0.3~2mm 翹曲量：±500um	Wafer diameter：12". Wafer thickness：0.3~2.0mm Warpage：±500um
控制系統 System Control Features	PC Base + PLC + 大型人機介面顯示	PC Base + PLC + Large interface display.
剝膜模組 Peeling Module	剝膜尺寸：8"/12" 膠帶尺寸： 50mm寬, Max130mm (3"內管)	Peeling Size：8"/12". Tape size: 50mm wide, Max130mm (3" inner tube)
產能 Capacity	WPH：30~40片 (依據製程參數)	WPH：30~40pcs (depend on process parameters)
環境要求 Clean room	室溫22°C ± 2°C 濕度55% ± 5% 無塵室等級Class 1000	Temperature：22°C ± 2°C Humidity：55% ± 5% RH Clean room：Class 1000
機台外型 Dimension	L1868 x W1600 x H1810mm	L1868 x W1600 x H1810mm
公共設備 Utilities	氣壓：0.6Mpa (乾淨乾燥AIR，口徑:3/8PT快速接頭) 機台電源：AC220V 3Φ 60HZ 可依客戶要求提供SECS GEM300服務	Pneumatic pressure：0.6Mpa (clear and dry AIR，Inlet tube:3/8"PT with one touch fitting). Power：AC220V 3Φ 60HZ. The SECS GEM300 service is available upon request.

Due to C SUN continuing efforts to improve their systems, these specifications are subject to change without notice.
 受長期研發需要，本公司保有規格修改之權利，恕不另行通知

DM2022Q3-000-TW